ML9484

Static, 1/2 Duty, 1/3 Duty, 1/4 Duty 50 Outputs LCD Driver

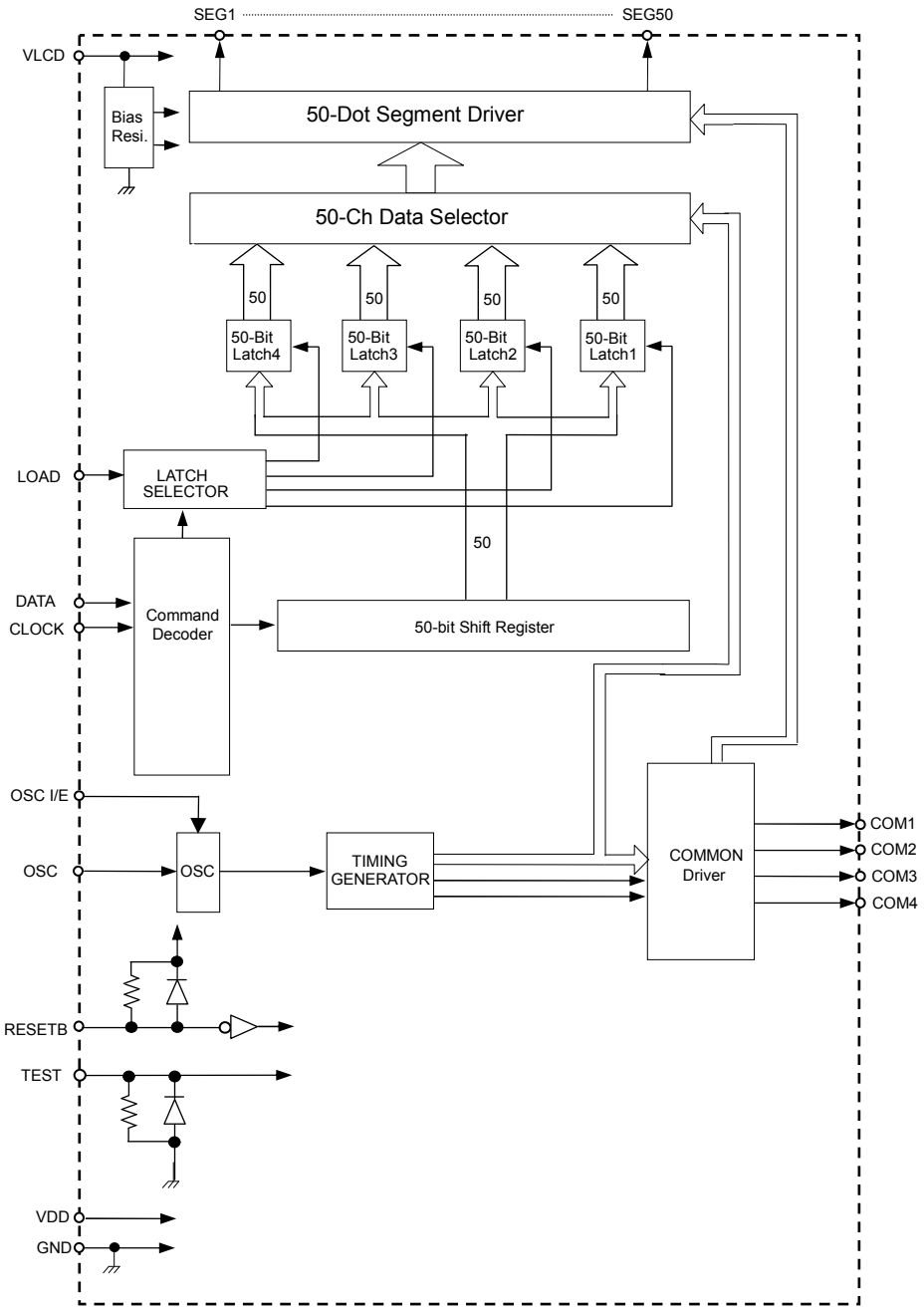
GENERAL DESCRIPTION

The ML9484 is an LCD driver LSI, consists of a 50-bit shift register, a 200-bit data latch, 50 sets of LCD drivers, and a common signal generation circuit.
It can directly drive an LCD up to 50 segments for static display, 100 segments for 1/2-duty display, 150 segments for 1/3-duty display, and 200 segments for 1/4-duty display.

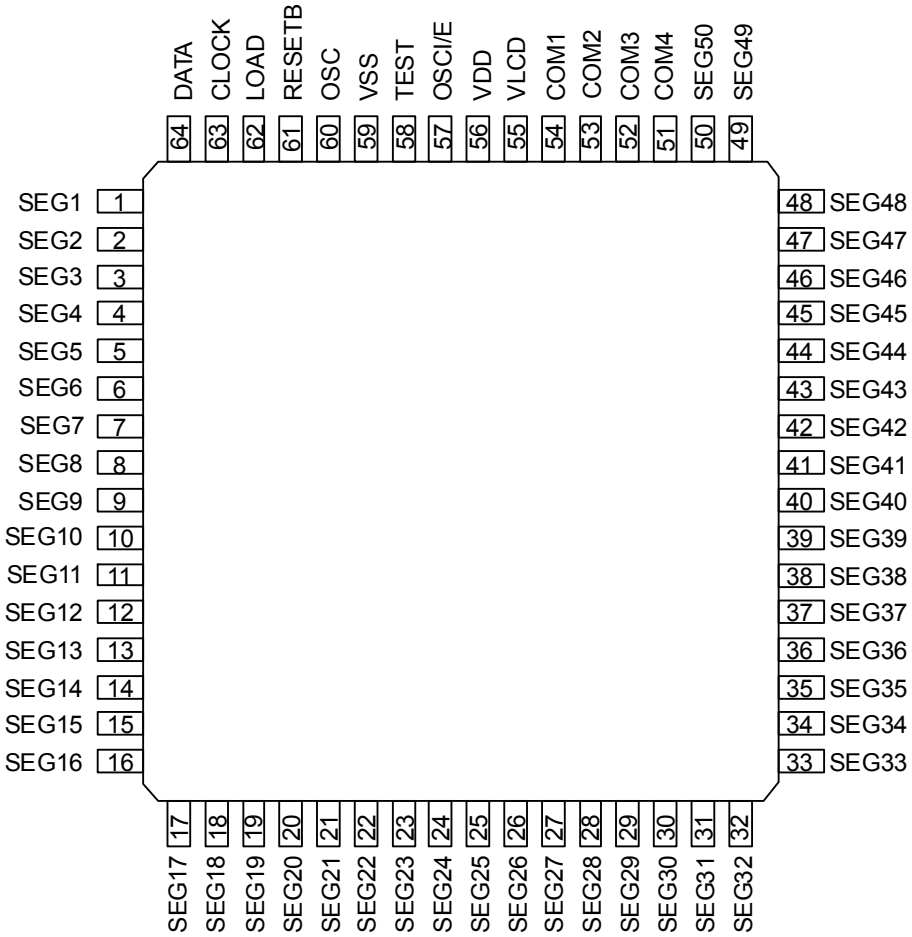
FEATURES

- Logic power supply voltage : 2.7 to 5.5 V
- LCD drive power supply voltage : 4.5 to 5.5 V
- Maximum number of segments
  Static display : 50 segments
  1/2-duty display : 100 segments
  1/3-duty display : 150 segments
  1/4-duty display : 200 segments
- Serially interfaces with the CPU using the three signal lines of DATA, CLOCK, and LOAD
- Selectable internal CR oscillator circuit or external clock input
- Built-in bias circuit
- Built-in common output intermediate-value voltage generation circuit
- Command-selectable A-waveform or B-waveform
- Package : 64-pin plastic TQFP

BLOCK DIAGRAM



PIN CONFIGURATION (TOP VIEW)



64-Pin Plastic TQFP

ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Condition	Rating	Unit
Logic power supply voltage	V_{DD}	Ta = 25°C	-0.3 to 6.0	V
LCD drive power supply voltage	V_{LCD}	Ta = 25°C	-0.3 to 6.0	V
Input voltage	V_I	Ta = 25°C	– 0.3 to V_{DD} + 0.3	V
Output short-circuit current	Is	Ta = 25°C	-2.0 to +2.0	mA
Power dissipation	P_D Ta	≦ 105°C	145 m	W
Storage temperature	T_{STG}	— -55	to +150	°C

Note: Do not use the ML9484 by short-circuiting one output pin to another output pin as well as to other pin (input pin, input/output pin, or power supply pin).

RECOMMENDED OPERATION CONDITIONS

Item	Symbol	Condition	Range	Unit
Logic power supply voltage	V_{DD}*	—	2.7 to 5.5	V
LCD drive power supply voltage	V_{LCD}*	—	4.5 to 5.5	V
OSC IN clock frequency	f_{CP1}	—	0.5 to 10	kHz
Data clock frequency	f_{CP2}	—	0.01 to 1.0	MHz
Operating temperature	T_a	—	-40 to +105	°C

Note(*): Use at $V_{DD} \leq V_{LCD}$.

ELECTRICAL CHARACTERISTICS

DC Characteristics

(V_{DD} = 2.7 to 5.5 V, V_{LCD} = 4.5 to 5.5 V, Ta= -40 to +105°C)

Item		Symbol	Condition	Min.	Typ.	Max. U	nit	Applicable pin
"H" input voltage		V_{IH}	— 0.8V	DD	— V	DD V		(*1)
"L" input voltage		V_{IL}	— G	ND	—	$0.2V_{DD}$	V	(*1)
Input leakage current 1		I_{L1}	V_I = V_{DD} or 0 V	-1 —		1	µA	(*2)
Input leakage current 2		I_{L2}	V_I = V_{DD}	-1	— 1		µA	RESET B
Pull-up current		I_{pu}	V_{DD} = 5.0V,V_I = 0 V	30	— 140		µA	RESET B
Driver ON resistor	Segment	V_{OHS}	V_{LCD} = 5V	— 5		15	kΩ	SEG1 to SEG50
	Common	V_{OHC}	V_{LCD} = 5V	— 5		12	kΩ	COM 1 to COM4
Static supply current		I_{DDS}	V_{DD}=V_{LCD}=5.5 V Input pin fixed to "H" or "L" Oscillation stopped, output no-load	—	1 7		µA	VDD
		I_{LCDS}		—	9 15		µA	VLCD
Dynamic supply current 1		I_{DD1}	V_{DD}=V_{LCD}= 5.5 V (*3) Clock OSC external input f_{CP1}=1.8kHz	—	2 10		µA	VDD
		I_{LCD1}		—	9 15		µA	VLCD
Dynamic supply current 2		I_{DD2}	V_{DD}=V_{LCD}= 5.5 V (*4) Internal oscillation=95Hz	—	53 82		µA	VDD
		I_{LCD2}		—	9 15		µA	VLCD

(*1) : DATA, CLOCK, LOAD, RESETB, OSC, OSC I/E
(*2) : DATA, CLOCK, LOAD, OSC, OSC I/E
(*3) : 1/4-duty, 1/3-bias, OSCI/E=”L”, Output pin no-load.
(*4) : 1/4-duty, 1/3-bias, OSCI/E=”H”, (F2, F, F0) = (0, 1, 1) 95 Hz, Output pin no-load.

Switching Characteristics

- OSC timing

(V_{DD} = 2.7 to 5.5 V, V_{LCD} = 4.5 to 5.5 V, Ta = -40 to +105°C)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit	Applicable pin
OSC IN clock frequency (External input)	f_{CP1}	Clock input from OSC. OSC I/E = "L"	0.5	1.8	10	kHz	OSC
Clock pulse width (External input)	t_{WCP1} 40			—	—	µs O	SC
Clock rise and fall time (External input)	t_{OSC}		—	— (*1)		µs O	SC
Internal clock frequency (Internal oscillation)	f_{OSC1}	OSC open. (F2, F1, F0)=(0, 0, 1) OSC I/E = "H"	18	28.8	44	kHz	OSC

The relation between OSC IN clock frequency and frame frequency is as the equation below.

$$f_{FRM} = f_{CP1} /24$$

(*1) t_{OSC} is a reference value.
The longer the clock rise and fall time, the more susceptible to extraneous noises around the threshold value. Make the rise as steep as possible. Reference value: max=2µs.

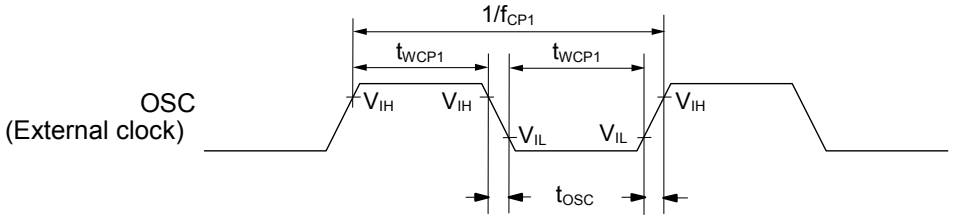
- Serial interface timing

(V_{DD} = 2.7 to 5.5 V, V_{LCD} = 4.5 to 5.5 V, Ta = -40 to +105°C)

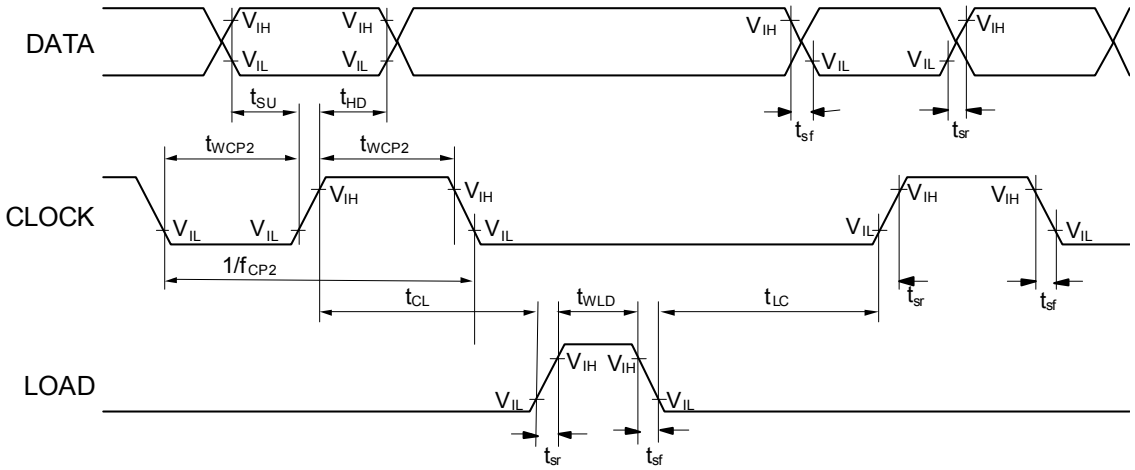
Item	Symbol	Condition	Min.	Typ.	Max.	Unit	Applicable pin
Data clock frequency	f_{CP2}		0.01	—	1	MHz	CLOCK
Data clock pulse width	t_{WCP2}		100	—	—	ns	CLOCK
Data setup time	t_{SU}		50	—	—	ns	DATA
Data hold time	t_{HD}		50	—	—	ns	CLOCK
CLOCK-LOAD timing	t_{CL}		100	—	—	ns	CLOCK
LOAD-CLOCK timing	t_{LC}		100	—	—	ns	LOAD
LOAD pulse width	t_{WLD}		100	—	—	ns	LOAD
Signal rise and fall time	tsr,tsf		— —		(*2)	ns	CLOCK,DATA, LOAD

(*2) tsr and tsf shall be reference values.
The longer the clock rise and fall time, the more susceptible to extraneous noises around the threshold value. Make the rise as steep as possible. Reference value: max=10ns.

Timing chart (OSC)

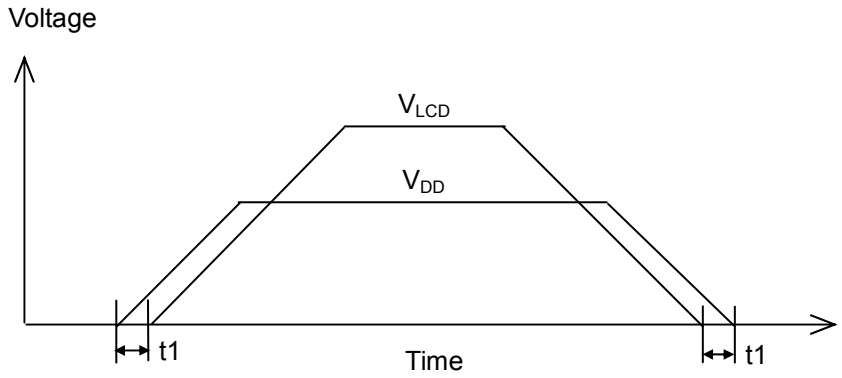


Timing chart (Serial interface)



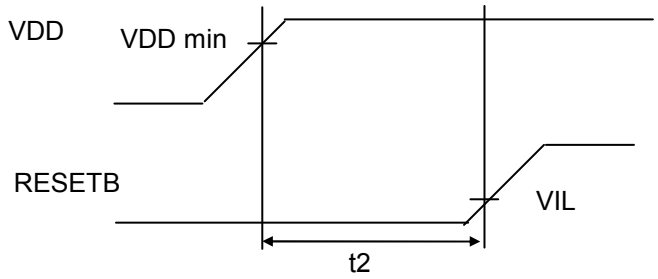
POWER ON/OFF TIMING

To turn on the power supply, raise the logic power supply first, then LCD drive power supply in order to prevent the IC from malfunctioning.
To fall the power supply, fall the LCD drive power supply first, then the logic power supply.
For a VDD pin ranging from 0 V to VDDmin, set VDD ≥ VLCD and t1 ≥ 0 [ns].



INITIALIZATION SIGNAL TIMING

Keep the RESETB pin at "L" level until the VDD reaches VDD min. (t2 ≥ 200[ns])

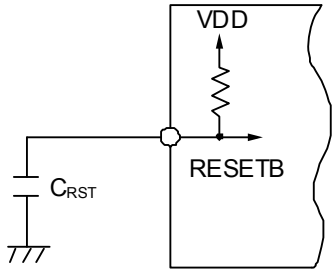


The value of the current of the pull-up resistor is specified for RESETB pin.
The customer needs to select an external capacitor that meets the timing requirements shown above.

PIN DESCRIPTIONS

Pad number	Symbol I/O		Description
1 to 50	SEG1 to SEG50	O	Outputs for LCD display. Connected to the segment pins on the LCD panel. In the display off mode, all the outputs are fixed to GND.
51 to 54	COM1 to COM4	O	Outputs for LCD display. Connected to the common pins on the LCD panel. In the display off mode, all the outputs are fixed to GND.
55	VLCD	-	Power supply pin for LCD driver.
56	VDD	-	Power supply pin for logic circuit.
57 O	SC I/E	I	This input selects whether to use the external clock input mode or to use the Internal oscillation mode. It has a schmitt circuit. When this pin is "H", the mode is the Internal Rf oscillation mode. When this pin is "L", the mode is the external clock input mode.
58 T	EST	I	IC test pin. Has a pull-down resistor built-in. Use it as it is connected to GND.
59 G	ND	-	Ground pin.
60 O	SC	I	Pin for oscillation. Has a Schmitt circuit built-in. Internal Rf oscillation mode: Set the OSCI/E pin to "H", open the OSC pin. External clock input mode: Set the OSCI/E pin to "L", input the external clock to the OSC pin.
61	RESETB	I	Reset signal input pin for initializing inside the IC. It has a schmitt circuit. The "L" level enables the reset. This pin has an Internal pull-up resistor. The pow er-on reset o peration is available by c onnecting an ex ternal capacitor. *1
62	LOAD	I	Input pin for the load signal of display data. It has a schmitt circuit. The display data in the shift register is transmitted as is to the segment driver for the "H " duration. When t his pi n is br ought int o "L ", the shift re gister i s disconnected from the segment driver. The display data in the shift register immediately before it become "L" is held in the data latch and transmitted to the segment driver.
63	CLOCK	I	Shift clock input pin for display data. It has a schmitt circuit. The display data input to the DATA pin is serially input to the shift register at the CLOCK signal rise.
64	DATA	I	Display data input pin. It has a schmitt circuit. Input the display data in the order of SEG50, SEG49, ... , SEG2, and SEG1. The display data turns on at "H" and turns off at "L".

*1: Reset circuit configuration

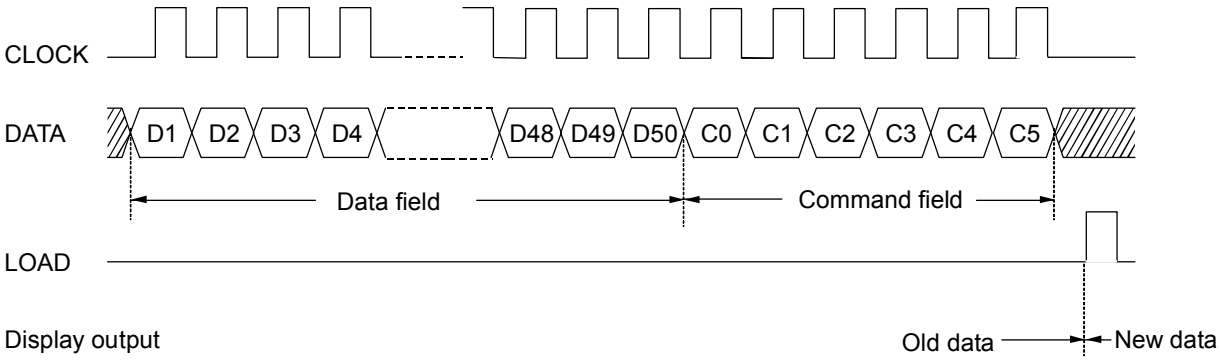


DESCRIPTION

Operation description

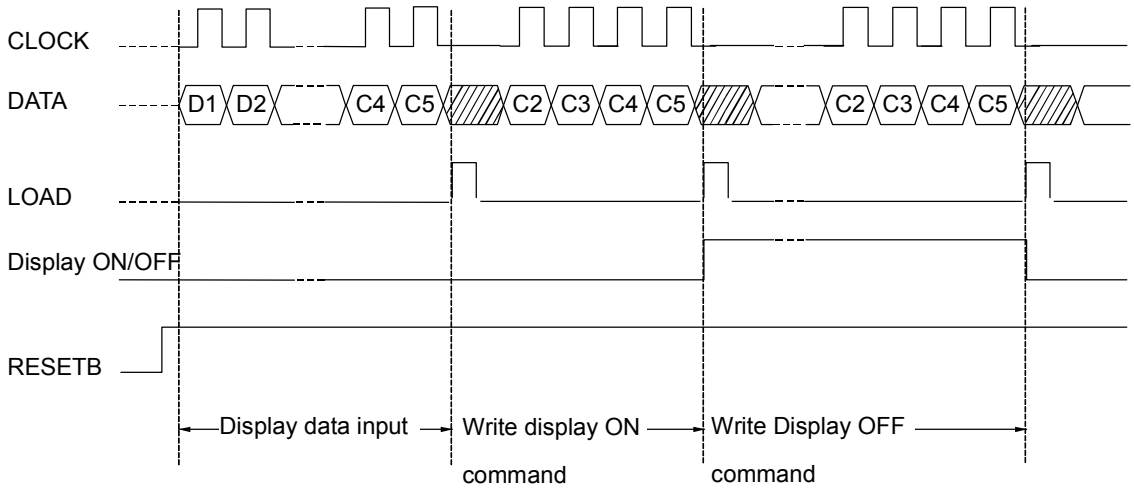
• Display data input

As described in the Data configuration section, the display data consists of the data field that corresponds to each segment on/off and the command field that indicates the display data input.
When inputting the display data, the "F1" command is set in the command field. When the "F2" to "F5" command is set in the command field, the display data in the data field becomes invalid.
The data input to the DATA pin is loaded to the shift register at the CLOCK pulse rise, transferred to the display data latch during the LOAD pulse at the "H" level, then output via the segment driver.



• Display on, Display off

The display becomes off at power-on reset. To display, write the display on command.
The display off is the command that makes all segments off. Writing the display off command turns off the lights regardless of the display data.
The display on is the command to release the display off. Writing the display on command returns the display to the original state.



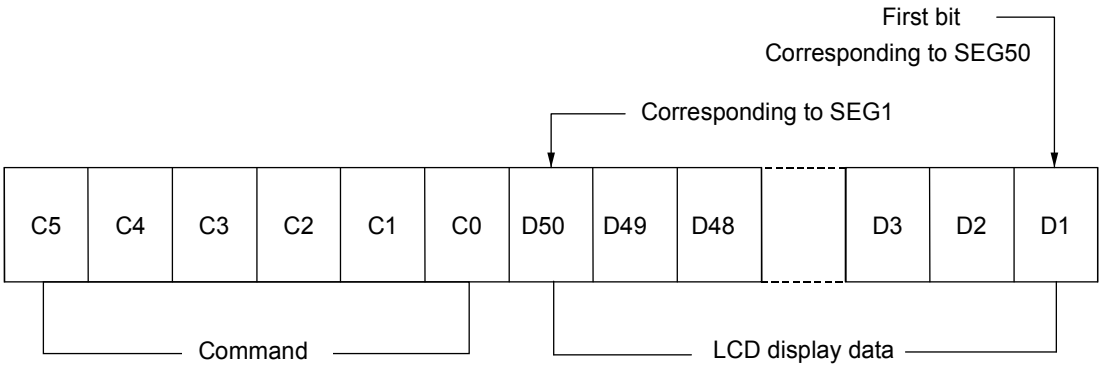
List of Commands

Command name	C5	C4	C3	C2	C1	C0	Operation
F0	0	0	0	x	x		Disabled
F1	0	0	1	Co1	Co0	x	Data write address setting (Co1,Co0)=(0, 0): Corresponding to common 1 (Co1,Co0)=(0, 1): Corresponding to common 2 (Co1,Co0)=(1, 0): Corresponding to common 3 (Co1,Co0)=(1, 1): Corresponding to common 4
F2	0	1	0	F2 (0)	F1 (0)	F0 (0)	Frame frequency setting (F2, F1, F0)=(0, 0, 0): 65Hz (F2, F1, F0)=(0, 0, 1): 75Hz (F2, F1, F0)=(0, 1, 0): 85Hz (F2, F1, F0)=(0, 1, 1): 95Hz (F2, F1, F0)=(1, 0, 0): 130Hz (F2, F1, F0)=(1, 0, 1): 150Hz (F2, F1, F0)=(1, 1, 0): 170Hz (F2, F1, F0)=(1, 1, 1): 190Hz (valid for Internal CR oscillation)
F3	0	1	1	BIAS (0)	WSEL (0)	x	LCD Bias setting BIAS="0" : 1/3-bias BIAS="1" : 1/2-bias LCD Driving Waveform setting WSEL="0" : A-Waveform WSEL="1" : B-Waveform
F4	1	0	0	D1 (0)	D0 (0)	x	Display Duty setting (D1, D0)=(0, 0): Static (COM1=COM2=COM3=COM4) (D1, D0)=(0, 1): 1/2-duty (COM1=COM3, COM2=COM4) (D1, D0)=(1, 0): 1/3-duty (COM2=COM4) (D1, D0)=(1, 1): 1/4-duty
F5	1	0	1	DSP (0)	x	x	Display on/off setting DSP="0" : Off（COM=SEG=GND） DSP="1" : On
F6	1	1	0	x	x		Disabled
F7	1	1	1	x	x		Disabled

x : Don't care
( ): Reset Value

Data configuration

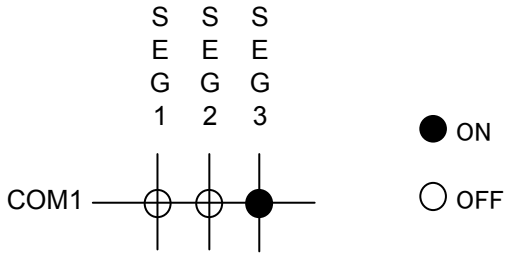
[In put data]

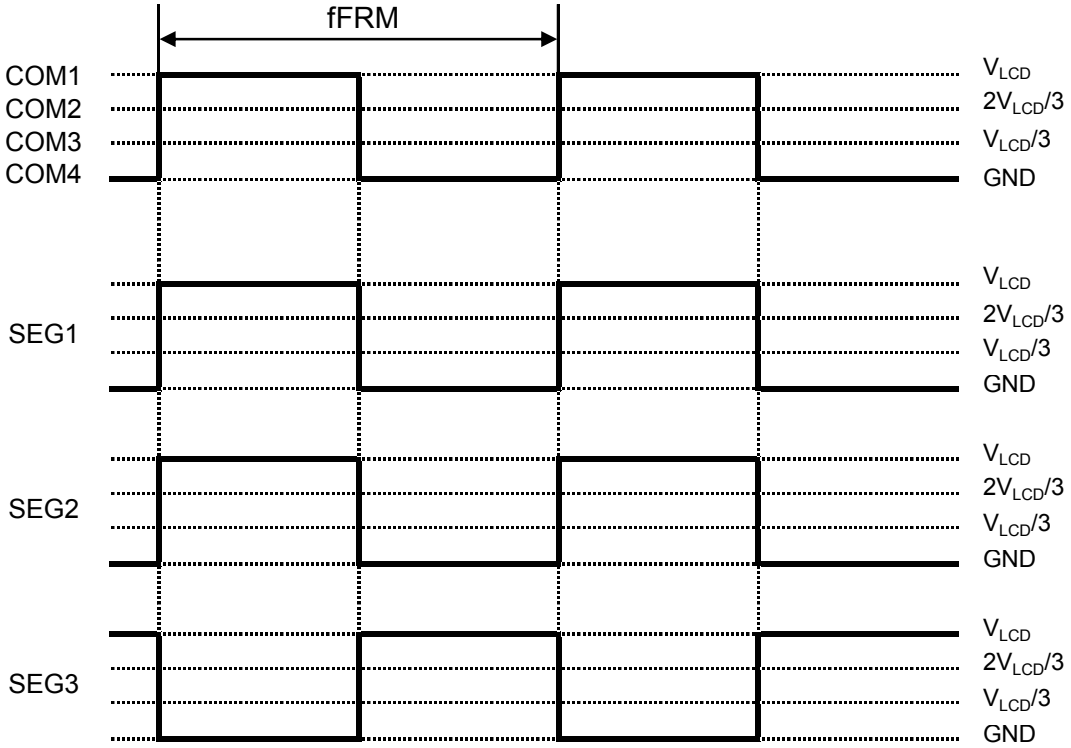


Note 1 : The commands F4 settings become valid when the least four bits of C2 to C5 are input.
(The bits from D1 to D50 and from C0 to C1 are not necessary.)
The commands F3 and F4 settings become valid when the least five bits of C1 to C5 are input.
(The bits from D1 to D50 and from C0 are not necessary.)
The commands F2 settings become valid when the least six bits of C0 to C5 are input.
(The bits from D1 to D50 are not necessary.)
Note 2 : If the dummy bit is needed for the reason of number of transfer bits, put it on the first bit side.
Note 3 : The command execution follows the contents of the C5 to C0 registers immediately before the LOAD becomes "H".

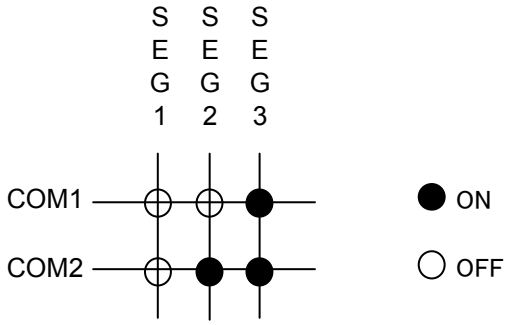
LCD Driving Waveform

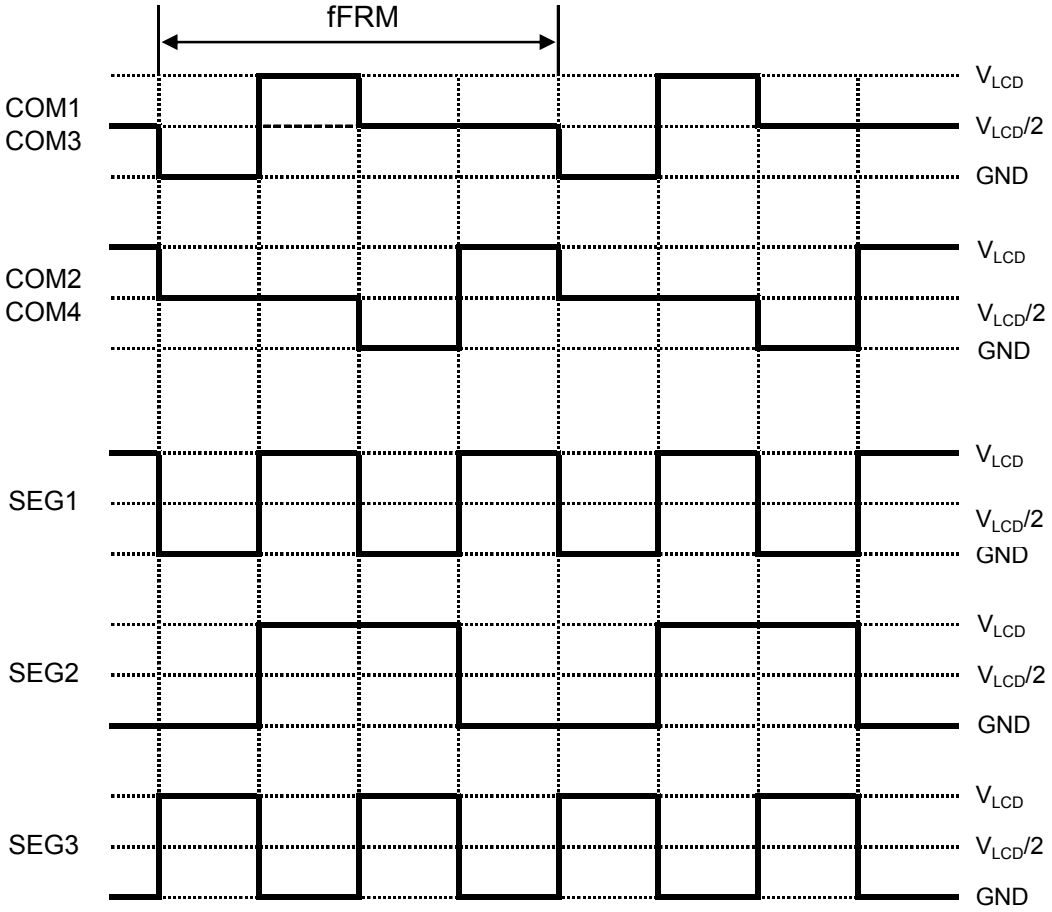
• Static mode (same as A-waveform and B-waveform)



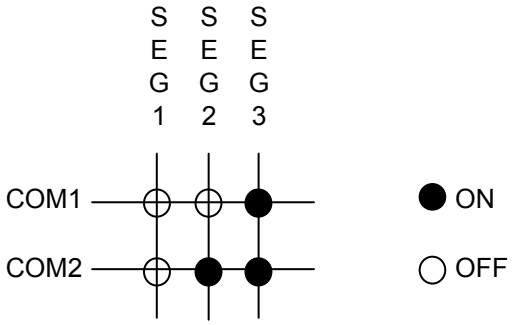


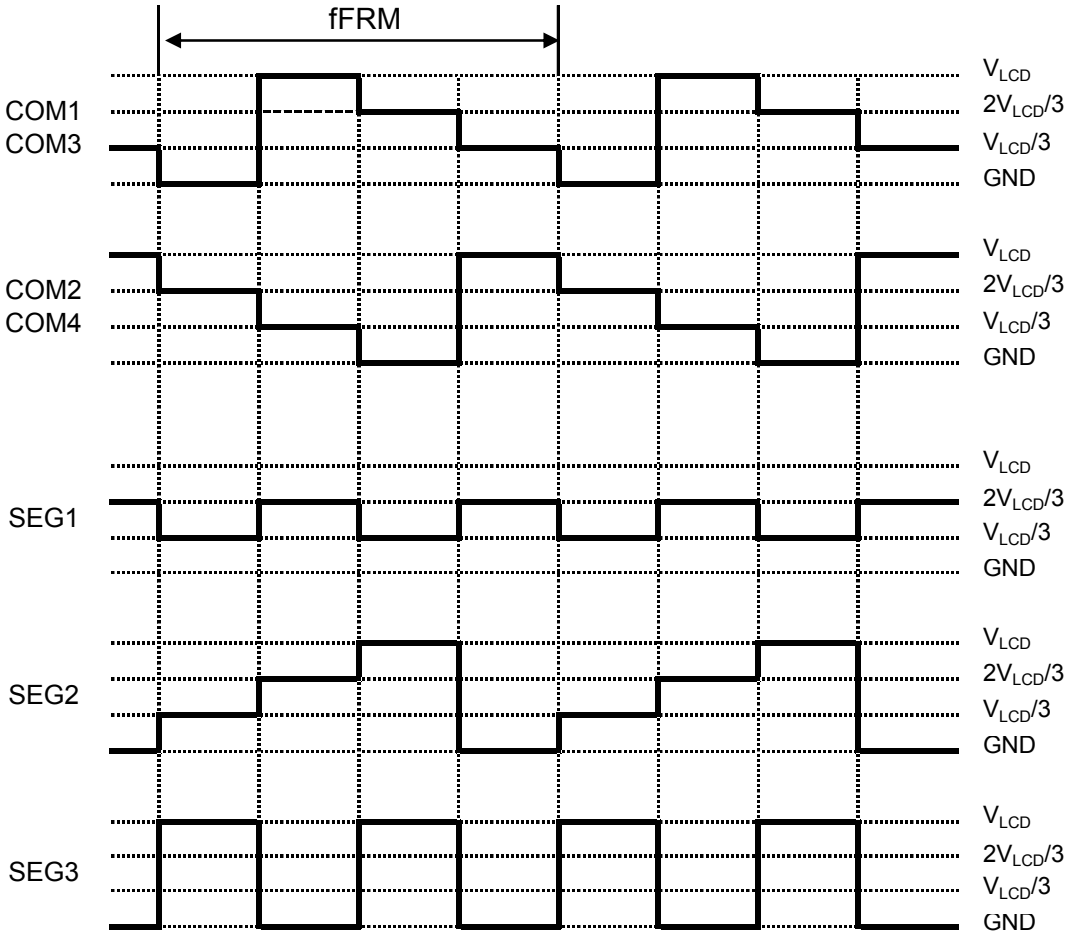
• 1/2-duty, 1/2-bias mode (A-waveform)



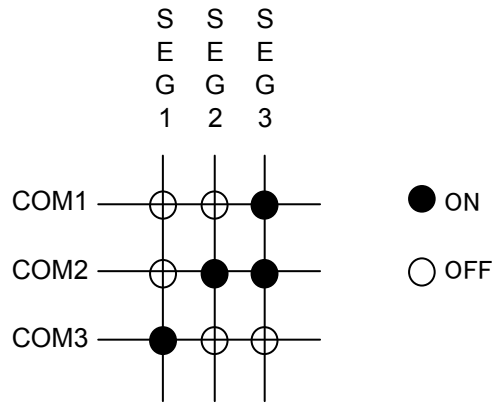


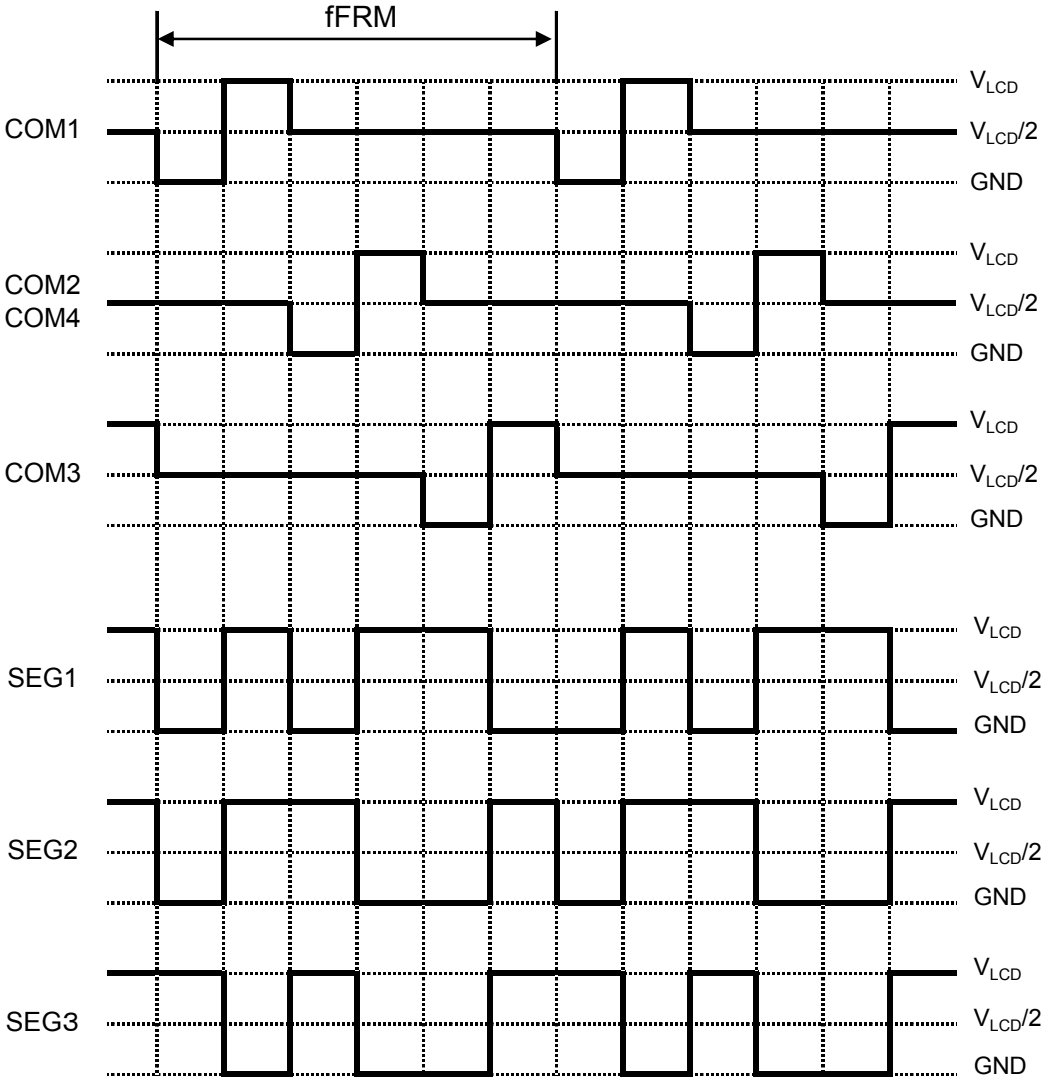
• 1/2-duty, 1/3-bias mode (A-waveform)



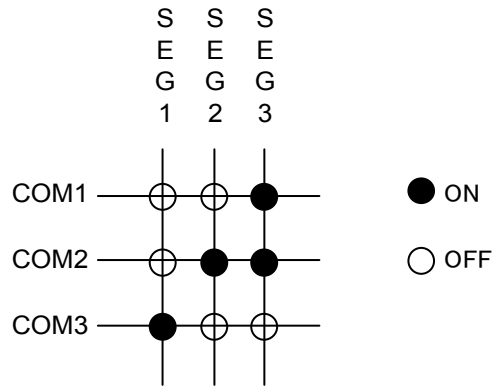


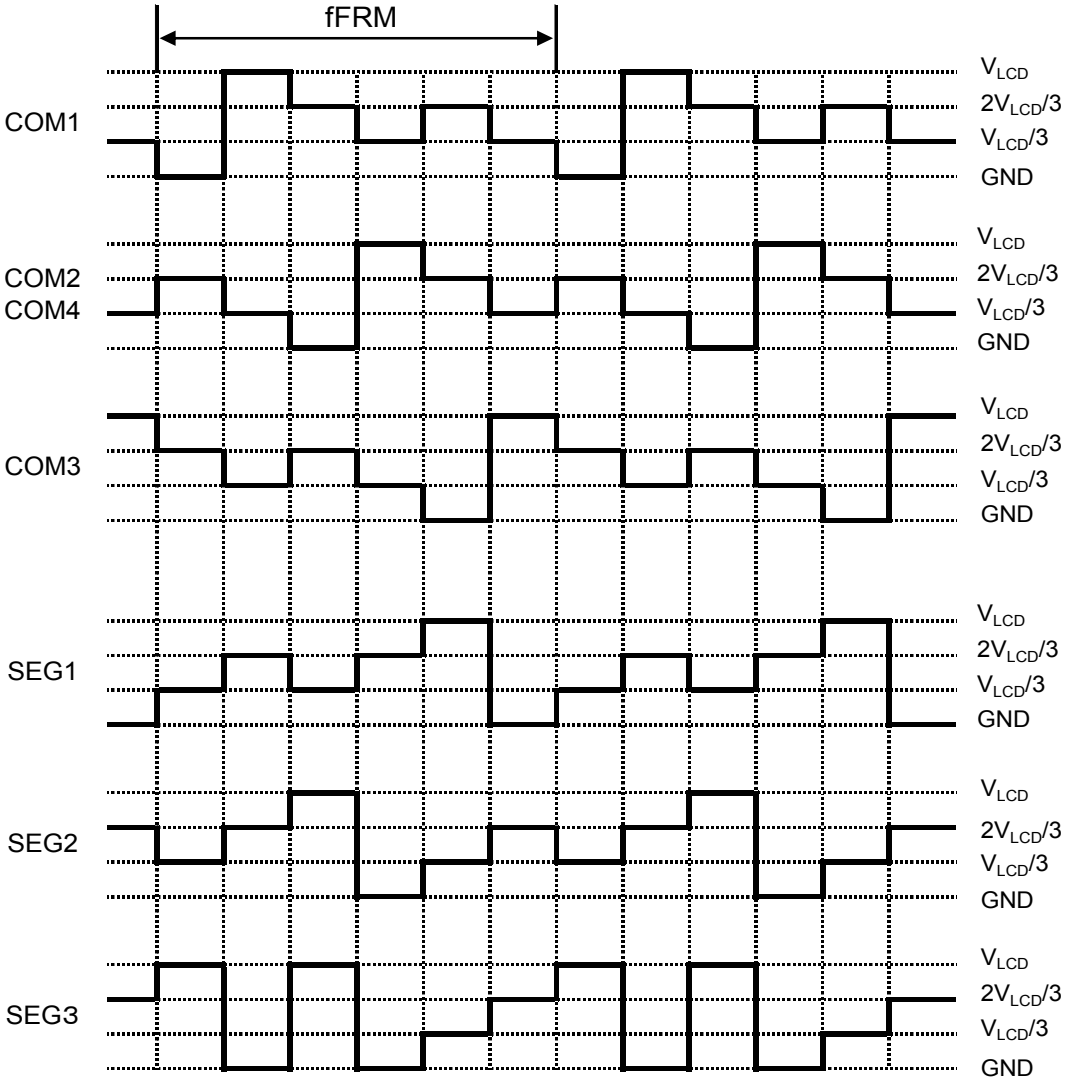
• 1/3-duty, 1/2-bias mode (A-waveform)



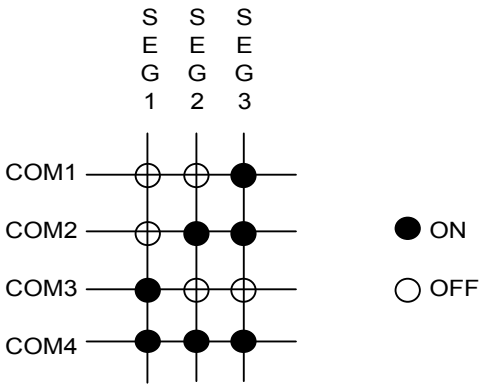


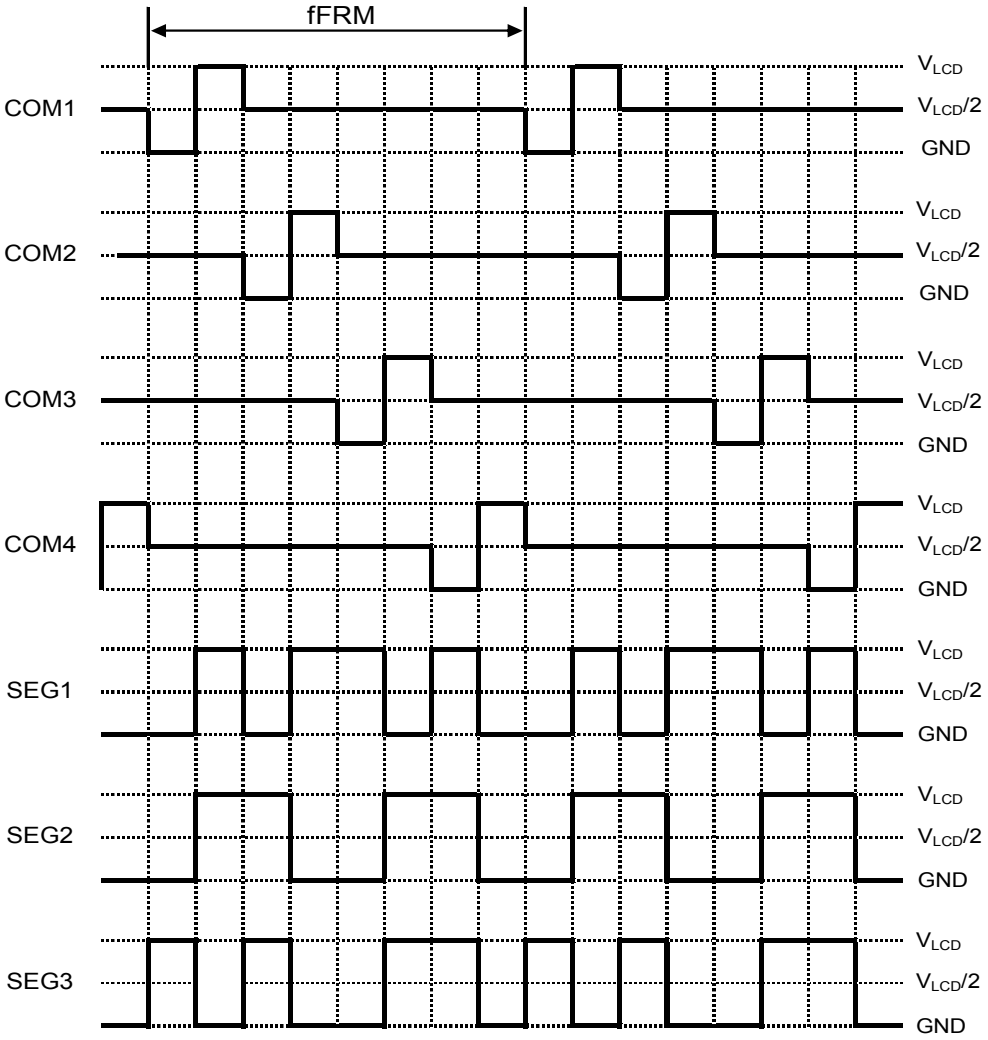
• 1/3-duty, 1/3-bias mode (A-waveform)



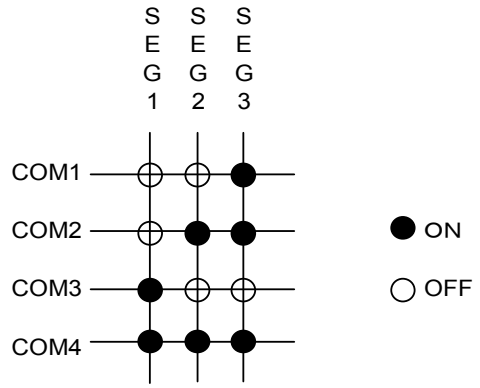


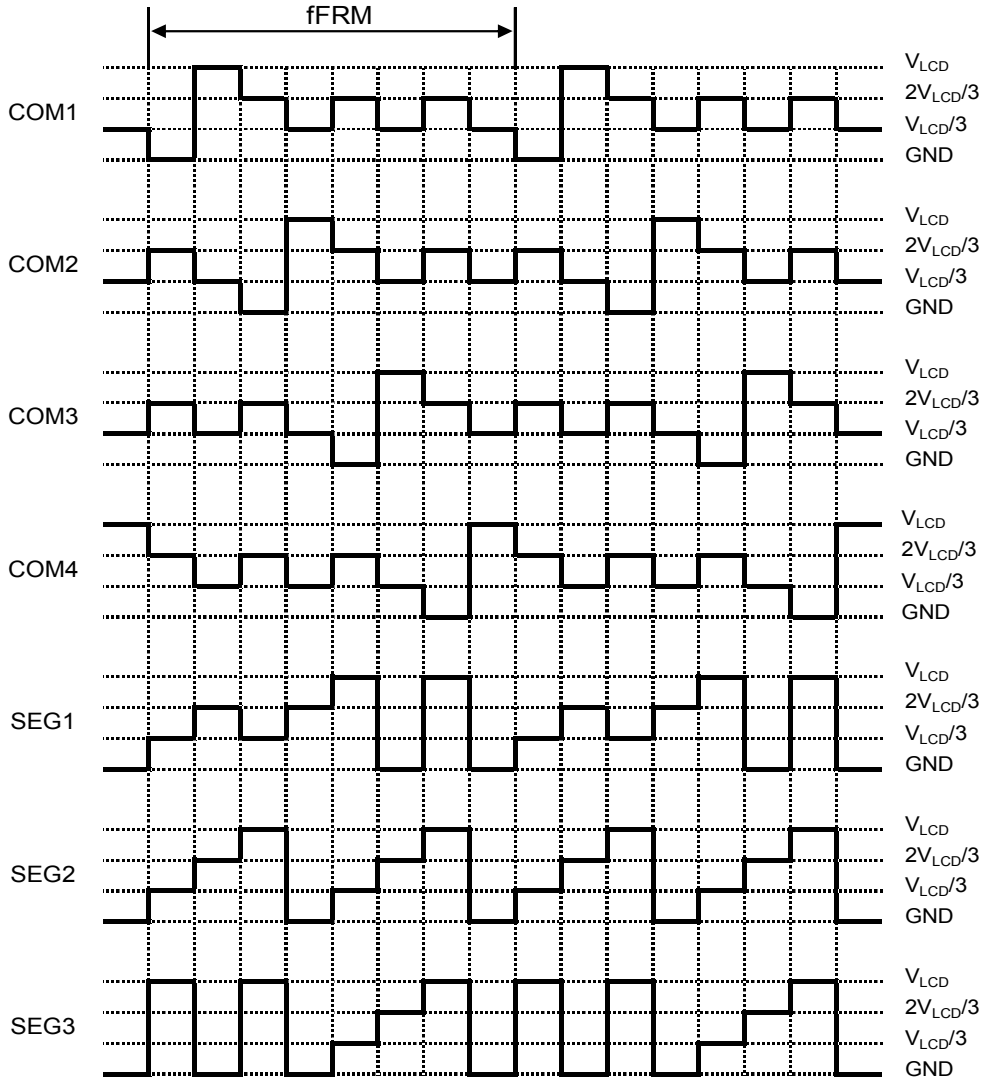
• 1/4-duty, 1/2-bias mode (A-waveform)



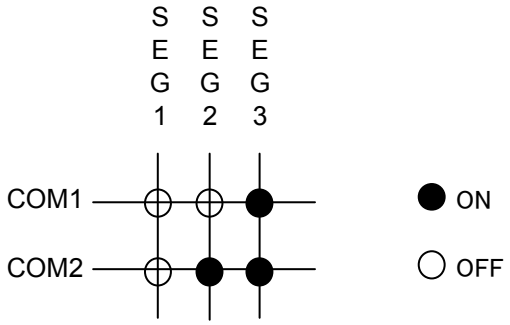


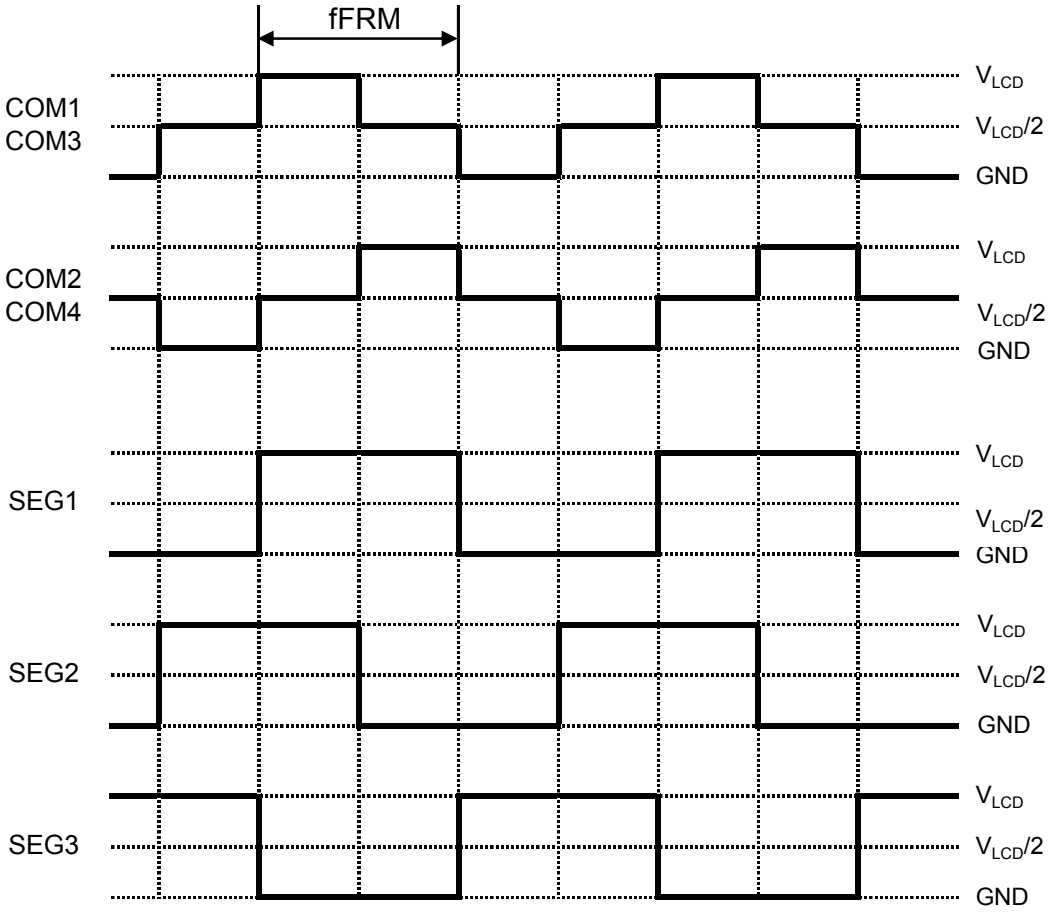
• 1/4-duty, 1/3-bias mode (A-waveform)



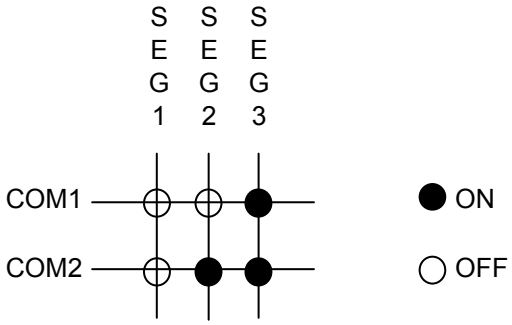


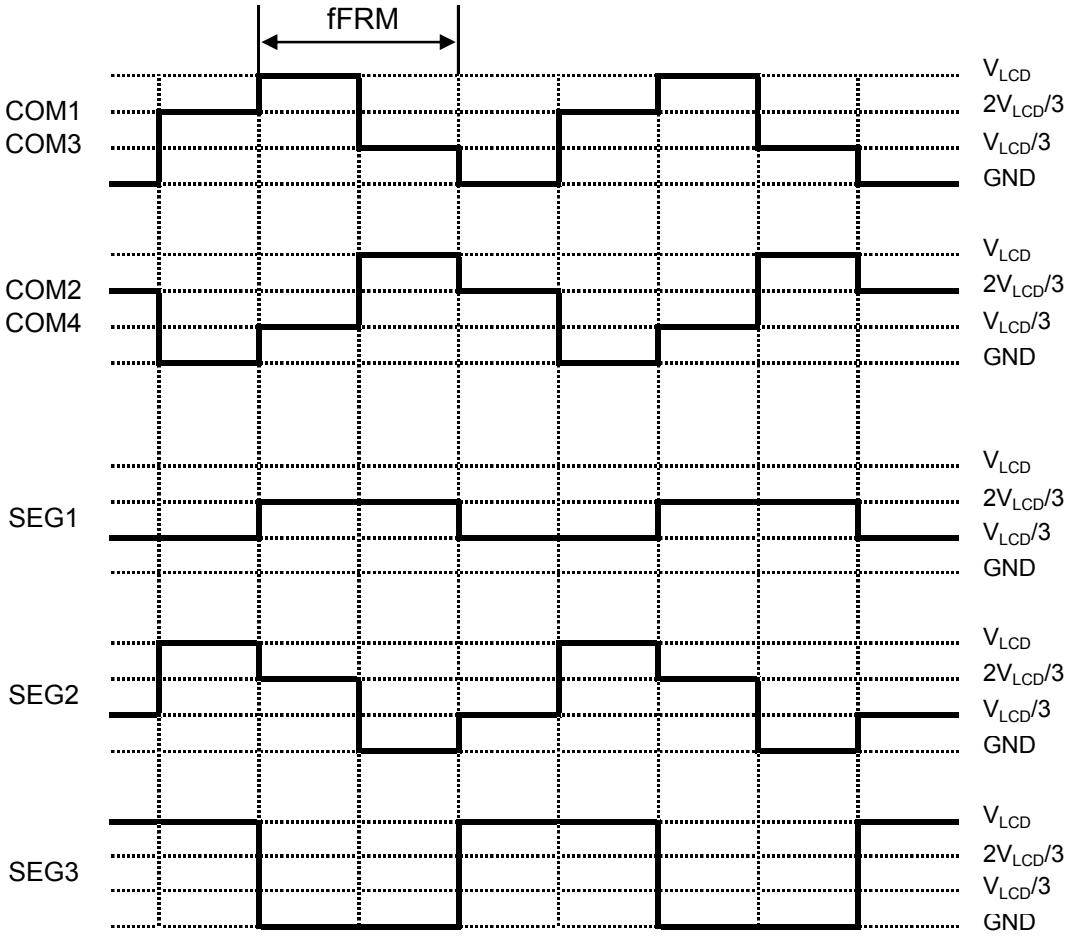
• 1/2-duty, 1/2-bias mode (B-waveform)



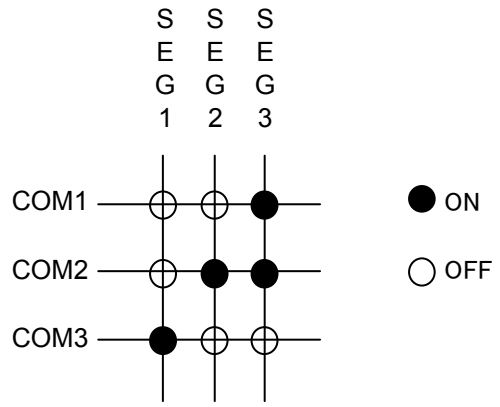


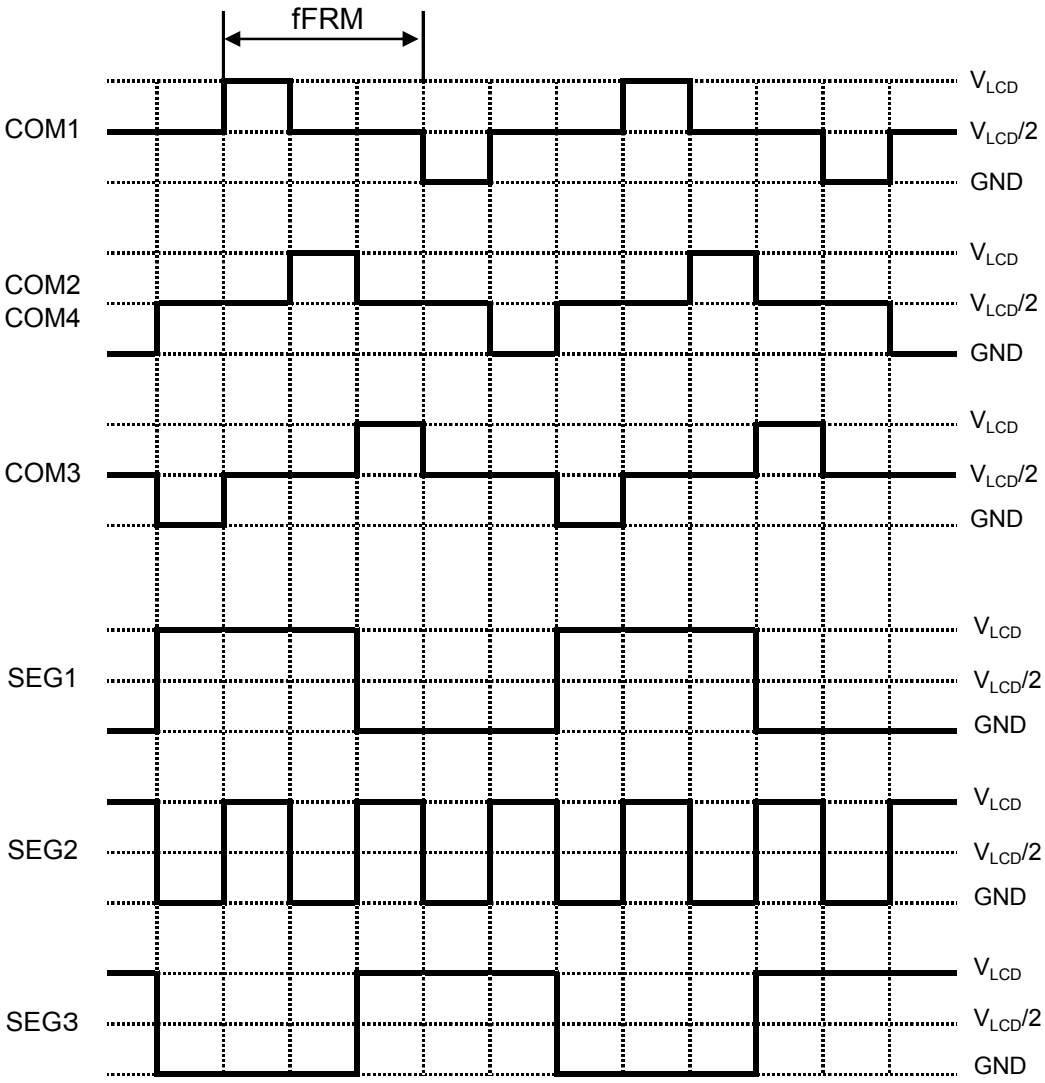
• 1/2-duty, 1/3-bias mode (B-waveform)



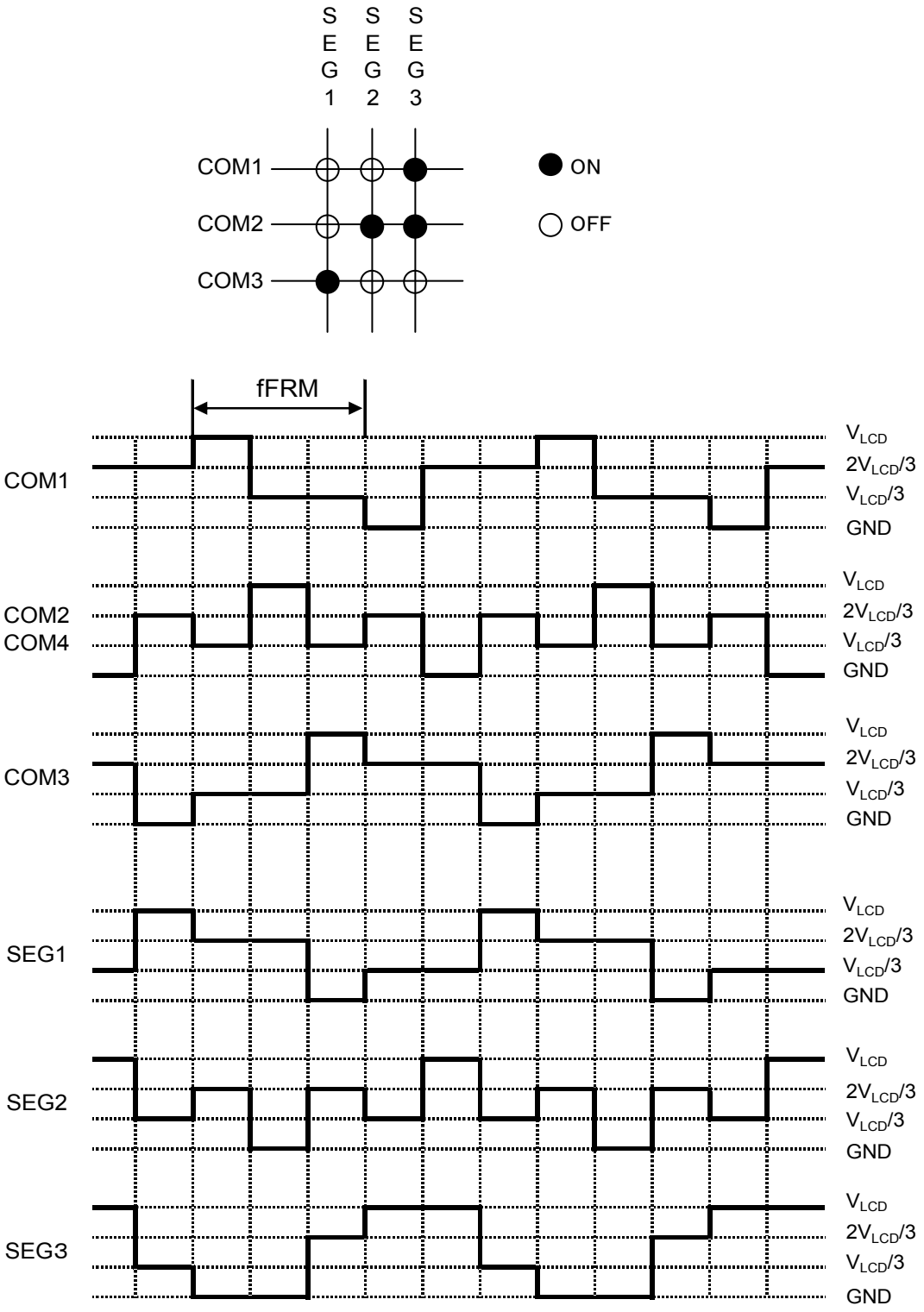


• 1/3-duty, 1/2-bias mode (B-waveform)

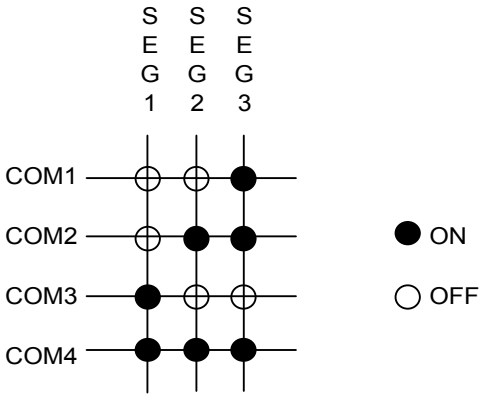


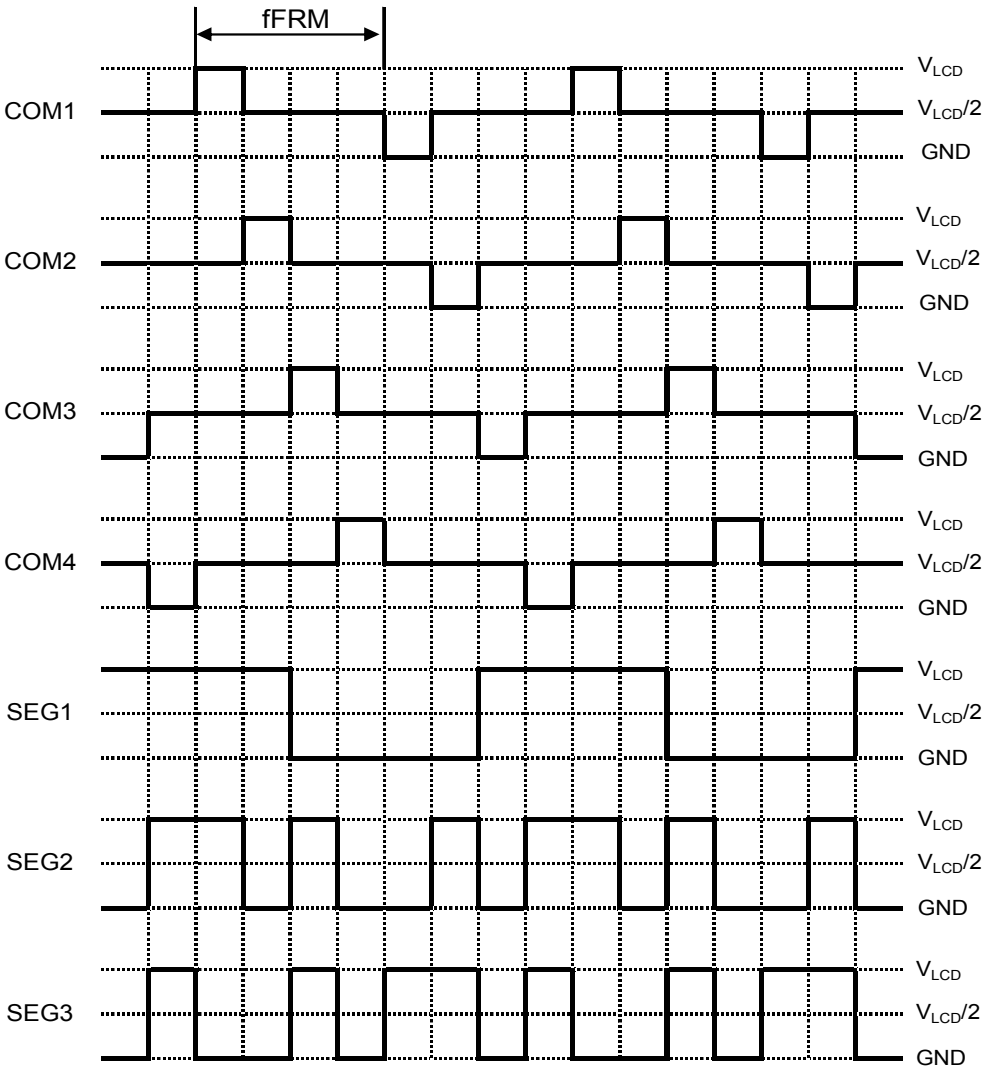


• 1/3-duty, 1/3-bias mode (B-waveform)

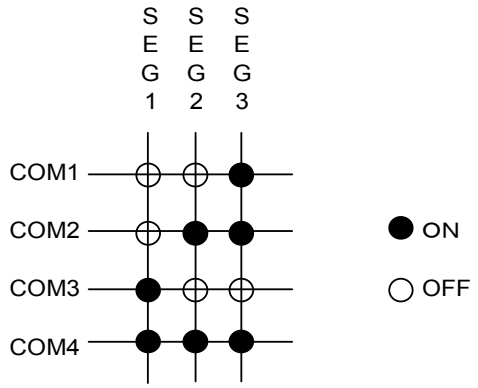


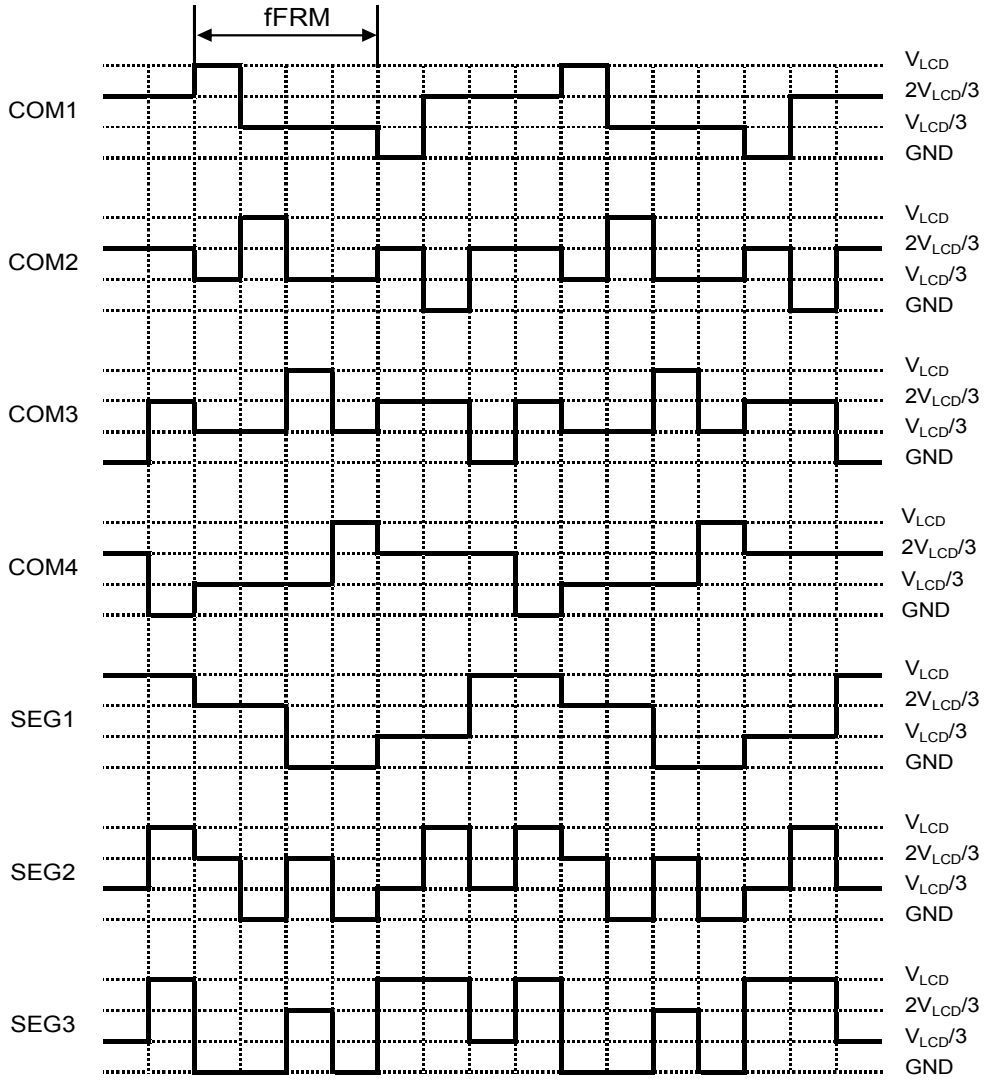
• 1/4-duty, 1/2-bias mode (B-waveform)



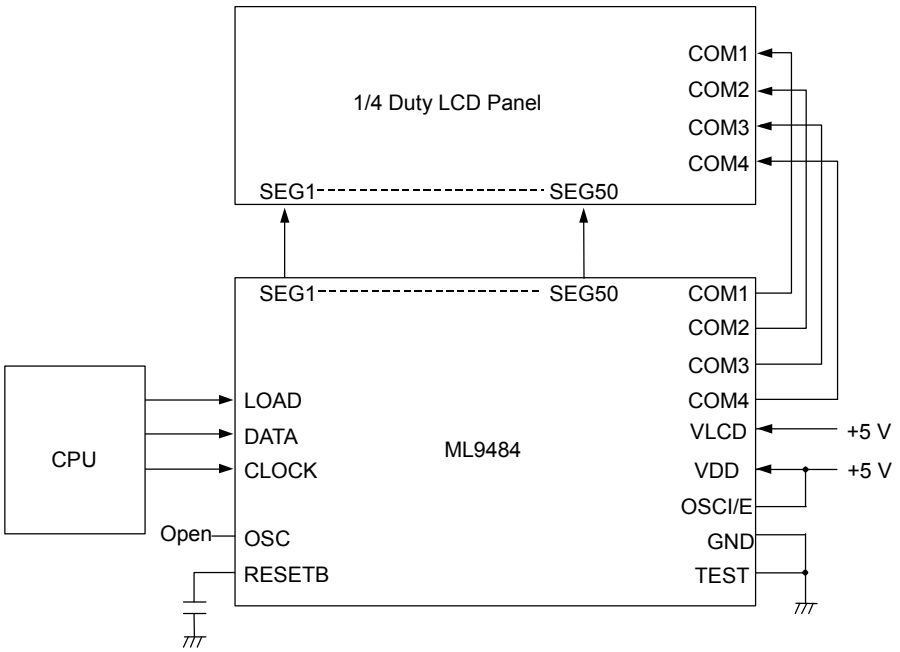


• 1/4-duty, 1/3-bias mode (B-waveform)





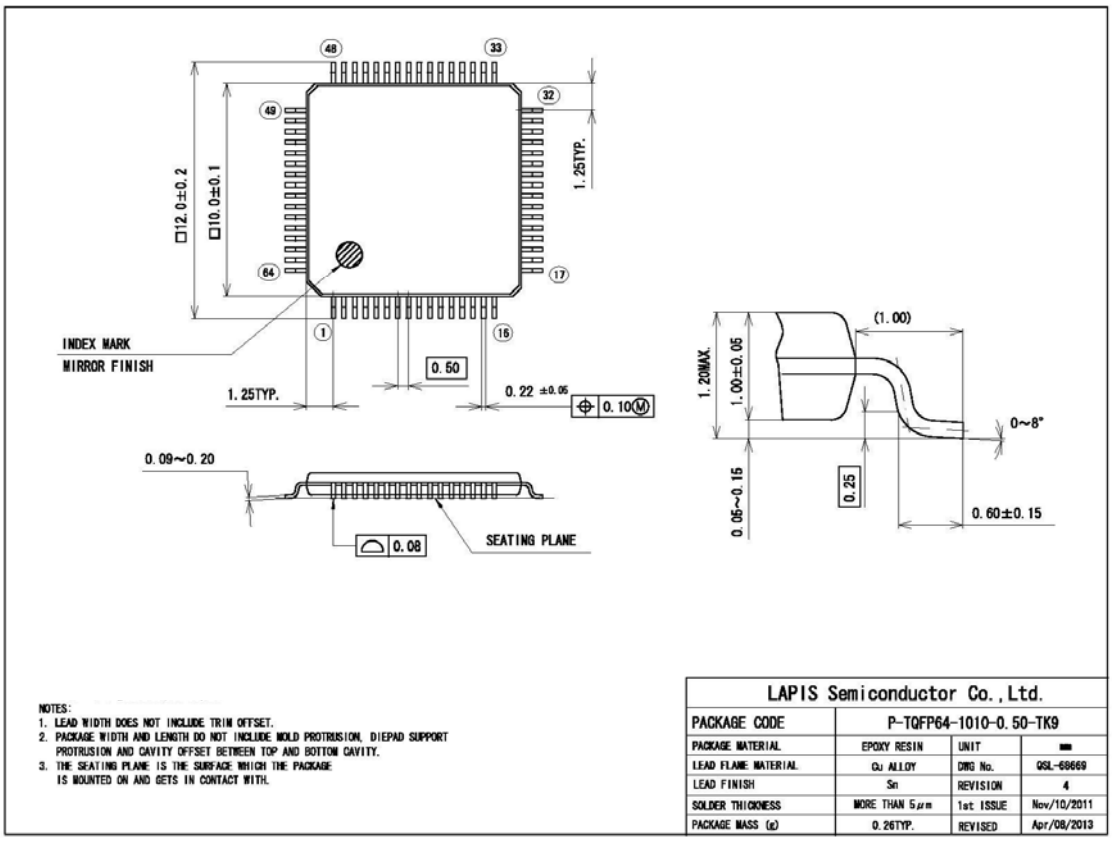
EXAMPLE OF APPLICATION CIRCUIT



REFRESH

Although t he ML 9484 h olds operat ion s tate by co mmands, ex cessive e xternal noise might c hange t he internal state.
On a chip-mounting and system level, it is necessary to take countermeasures against preventing noise from occurring. It is recommended to use the refresh sequence periodically to control sudden noise.

PACKAGE DIMENSIONS



Notes for Mounting the Surface Mount Type Package

The surface mount type packages are very susceptible to heat in reflow mounting and humidity absorbed in storage. Therefore, before you perform reflow mounting, contact ROHM's responsible sales person for the product name, package name, pin number, package code and desired mounting conditions (reflow method, temperature and times).

REVISION HISTORY

Document No.	Issue Date	Page		Description
		Previous Edition	New Edition	
FEDL9484-01	Dec .25, 2013	–	–	Final edition 1 issued

NOTES

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